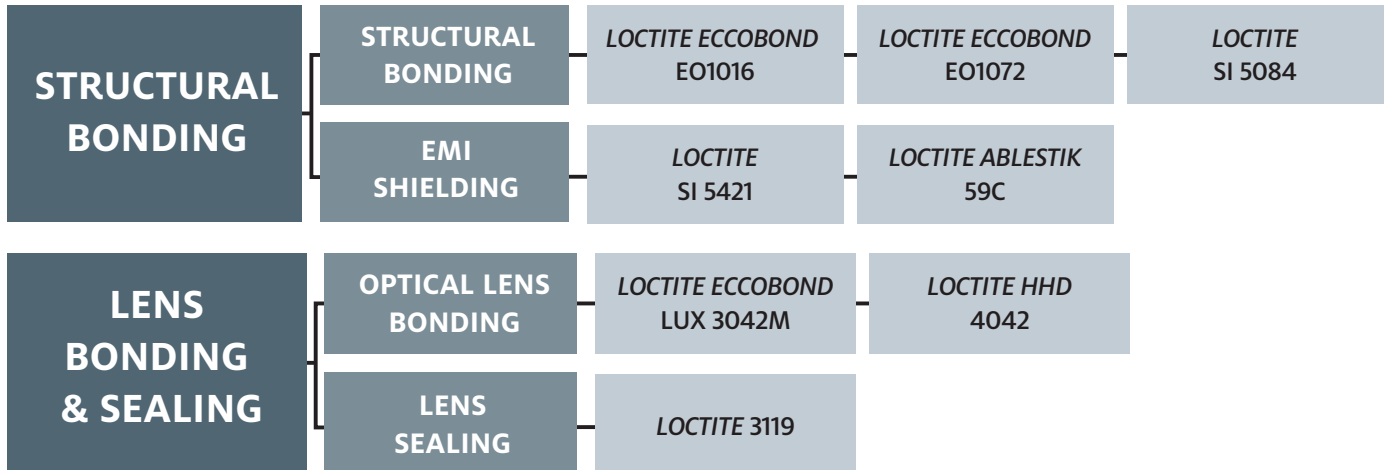


Structural Bonding



Structural Bonding

PRODUCT	TECHNOLOGY	APPLICATION	KEY ATTRIBUTES	VISCOSITY (cP)	GLASS TRANSITION TEMPERATURE, T _g (°C)	CURE TYPE	CURE SCHEDULE
STRUCTURAL BONDING							
<i>LOCTITE ECCOBOND</i> EO1016	Epoxy	Encapsulant	<ul style="list-style-type: none"> Good adhesion to metal and plastics, especially nickel and FR4 Fast curing Excellent shelf stability 	62,000	126	Heat	20 min. at 150°C
<i>LOCTITE ECCOBOND</i> EO1072	Epoxy	Encapsulant	<ul style="list-style-type: none"> High T_g Low extractable ionics High performance Good shelf life Fast curing 	100,000	135	Heat	5 min. at 140 – 150°C
<i>LOCTITE SI</i> 5084	Silicone	Gasketing	<ul style="list-style-type: none"> Highly flexible Non-corrosive Enhances load bearing and shock absorbing characteristics of the bond area 	Paste	N/A	UV & RT	UV + Moisture
EMI SHIELDING							
<i>LOCTITE SI</i> 5421	Silicone	Bonding/Gasketing	<ul style="list-style-type: none"> Electrically conductive RTV silicone Bonding and gasketing of EMI/RFI shielded enclosures 	Paste	N/A	RTV	Tack free in 60 min. at 23 ± 2°C / 50 ± 5% RH
<i>LOCTITE ABLESTIK</i> 59C	Silicone	Assembly	<ul style="list-style-type: none"> Electrically conductive silicone EMI / RFI shielding Thermally conductive High flexibility High tack Can be used with a variety of catalysts 	N/A	N/A	Heat	6 hr. at 150°C

Lens Bonding & Sealing

PRODUCT	TECHNOLOGY	APPLICATION	KEY ATTRIBUTES	VISCOSITY (cP)	GLASS TRANSITION TEMPERATURE, T _g (°C)	CURE TYPE	CURE SCHEDULE
OPTICAL LENS BONDING							
<i>LOCTITE ECCOBOND LUX</i> 3042M	Acrylate	Assembly	<ul style="list-style-type: none"> One component Dual cure system Good adhesion on PEI plastics, FR4 and various other substrates 	85,000	114	UV & Heat	UV + 30 min. at 120°C
<i>LOCTITE HDD</i> 4042	Epoxy/Acrylate	Assembly	<ul style="list-style-type: none"> One component Dual cure system Good adhesion on PEI plastics, FR4 and various other substrates 	125,000	145	UV & Heat	UV + 60 min. at 120°C
LENS SEALING							
<i>LOCTITE ABLESTIK</i> 3119	Epoxy	Bonding	<ul style="list-style-type: none"> Low temp cure Excellent adhesion on wide range of substrates Very low shrinkage 	7,000 – 23,000	110	Heat	60 min. at 100°C or 20 min. at 75°C

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Thermal Management Materials



PRODUCT	TECHNOLOGY	APPLICATION	KEY ATTRIBUTES	THICKNESS (in/mm)	SHORE HARDNESS (SHORE 00)	THERMAL CONDUCTIVITY (W/m-K)
THERMAL PAD						
BERGQUIST GAP PAD TGP 3004SF	Silicone Free	Thermal Pad	<ul style="list-style-type: none"> Silicone-Free formulation 0.25 mil PET provides easy disassembly, leaving no residue Tacky side allows for ease of handling and placement 	0.254 – 3.175	70	3.0
BERGQUIST GAP PAD TGP HC5000	Silicone	Thermal Pad	<ul style="list-style-type: none"> High-compliance Low compression stress Fiberglass reinforced for shear and tear resistance 	0.508 – 3.175	35	5.0
EMI ABSORPTION						
BERGQUIST GAP PAD TGP EMI1000	Silicone	EMI Absorbing	<ul style="list-style-type: none"> EMI absorbing Highly conformable Low hardness Fiberglass reinforced for puncture, tear and shear resistance Electrically isolating 	0.508 – 3.175	5	1.0
GAP FILLER						
BERGQUIST GAP FILLER TGF 3500LVO (TWO PARTS)	Silicone	Gap Filler	<ul style="list-style-type: none"> Low volatility for outgassing sensitive applications Ultra-conforming with excellent wet-out for low stress interface on applications 100% solids - no cure by-products 	N/A	40	3.5
BERGQUIST GAP FILLER TGF 3600	Silicone	Gap Filler	<ul style="list-style-type: none"> Thixotropic nature makes it easy to dispense Two-part formulation for easy storage Ultra-conforming - designed for fragile and low stress applications Ambient or accelerated cure schedules 	N/A	35	3.6
BERGQUIST GAP FILLER TGF 4000	Silicone	Gap Filler	<ul style="list-style-type: none"> Thickness variations Little to no stress 100% Solids – No cure by-products Excellent low and high temperature chemical and mechanical stability 	N/A	75	4.0